

Title (en)

Method for bonding electronic components on a substrate by means of pressure sintering

Title (de)

Verfahren zur Befestigung elektronischer Bauelemente auf einem Substrat durch Drucksintern

Title (fr)

Procédé pour la fixation de composants électroniques au-dessus d'un substrat au moyen de frittage par pression

Publication

EP 0764978 B1 20071024 (DE)

Application

EP 96112831 A 19960808

Priority

DE 19533561 A 19950911

Abstract (en)

[origin: EP0764978A2] To mount and secure electronic components to a substrate, by pressure sintering, a layer (3) of a powder which can be sintered is applied to a contact surface of the component and/or a contact surface (11) of the substrate (1). The contact surfaces are brought together, under pressure, and are heated to the sintering temp. to sinter the bonding layer (3). The layer (3) is deposited by evaporation and condensation of a metal where, at a gas pressure of 100-1000 Pa, a nano-crystal metal powder is formed on the surface(s). The layer (3) is of silver, deposited in a He atmosphere to grow and develop into the layer structure.

IPC 8 full level

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Cited by

DE102017113153A1; DE102008055134A1; DE102017113153B4; WO2008006340A1; US9214442B2; US8587116B2; US8835299B2; US8999758B2

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